Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L5	72	wafer near scale and (edge or perimeter) near3 (seal or sealing or sealed or barrier or hermetic$4)	US-PGPUB; USPAT	OR	ON	2005/07/22 14:03
L2	533	(concentric or plural or plurality) near (barrier or ring) same (chip or die or ic or wafer or substrate) near2 (plural or plurality or multi or multiple or stack or stacked or stacking or three near dimensional)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 13:36
L3	64	(concentric) near (barrier or ring or rib or ridge) same (chip or die or ic or wafer or substrate) near2 (plural or plurality or multi or multiple or stack or stacked or stacking or three near dimensional)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 13:36
S99	195	(three near dimension$3 or stack or stacking or stacked) near (substrate or wafer) and ring near3 (edge or periphery or peripheral or surrounding or circumscrib$3) and (wiring or interconnect$3 or trace or damascene)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 10:45
S98	215	(multi or multiple or plural or plurality or several or second or third or secondary) near2 (wafer or substrate) near2 (stack or stacking or stacked or three near dimension$3) near3 (chip or ic or integrated adj circuit or module)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 10:30
S95	23	(multi or multiple or plural or plurality or several or three near dimensional) near2 (wafer or substrate) near2 (stack or stacking or stacked) near3 (chip or ic) same (interconnect$3 or wiring or damascene or trace)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 09:45
S94	15	(multi or multiple or plural or plurality or stack or stacked or stacking) near2 (wafer or substrate) near3 (chip or ic) same (interconnect$3 or wiring or damascene) same (ild or interlayer near dielectric or inter-layer near dielectric or imd or inter-metal adj dielectric)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 09:39
S93	7599	(multi or multiple or plural or plurality or stack or stacked or stacking) near2 (wafer or substrate) near3 (chip or ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 09:37
S1	135	((die or wafer or chip) near2 (bond or bonding or attachment or attaching or bonded or attached) or flip adj chip) and (barrier or corrosion or contamination or crack or sealing or seal) near3 (edge or periphery or peripheral or outside or outer) near3 (metal or copper or cu or metallic or aluminum or gold or silver)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 09:36
S92	27	("6355501").URPN.	USPAT	OR	ON	2005/07/21 14:19
S88	58	("5455445").URPN.	USPAT	OR	ON	2005/07/21 14:10
S87	177	integrated adj chip and (multiple or multi or plural or plurality or several or stack or stacked or stacking) near3 (wafer or substrate) and (seal or sealed or sealing or barrier or protecting or protection or protected) near5 (edge or outside or outer or periphery or peripheral or circumscrib$3 or surrounding or exterior or surface)	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/21 13:09
S86	989	integrated adj chip and (multiple or multi or plural or plurality or several or stack or stacked or stacking) near3 (wafer or substrate)	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/21 13:08
S84	217	257/620.ccor.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/21 13:07
S85	6895	integrated adj chip	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/21 13:07
S83	142	438/462.ccor.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/21 11:40

S82	210	438/458.ccor.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/21 11:27
S80	29	438/456.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 11:03
S79	201	438/455.ccor. and (seal$3 or barrier or wall or ridge or spacer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 11:02
S77	248	438/108.ccor. and (seal$3 or barrier or wall or ridge or spacer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 09:30
S75	225	438/107.ccor. and (seal$3 or barrier or wall or ridge or spacer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 09:08
S72	4	(wafer or chip or die or substrate) near3 (edge or periphery or peripheral or circumscrib$3 or surround$3) near3 (barrier or seal or sealing or sealed) near4 (self or auto)	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/20 16:58
S71	361	(wafer or chip or die or substrate) near3 (edge or periphery or peripheral or circumscrib$3 or surround$3) near3 (barrier or seal or sealing or sealed) same (wafer or chip or die or substrate) near2 (three-dimension$3 or stack or stacked or stacking or bond or bonding or bonded) and (pad or electrode or terminal) near3 (join$3 or bond$3 or connect$3 or interconnect$3)	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/20 16:55
S65	17	("5448014").URPN.	USPAT	OR	ON	2005/07/20 15:56
S64	51	(wafer) near2 (scale or level) near4 (package or packaging) and (barrier or corrosion or contamination or crack or sealing or seal or ridge or hermetic or hermetically) near10 (edge or periphery or peripheral or outside or outer or border) near10 (metal or copper or cu or metallic or aluminum or al or nickel or ni or gold or au or silver or ag or solder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:44
S49	45	(wafer) near2 (scale or level) near4 (package or packaging) and (barrier or corrosion or contamination or crack or sealing or seal or ridge or hermetic or hermetically) near10 (edge or periphery or peripheral or outside or outer or border) near10 (metal or copper or cu or metallic or aluminum or al or nickel or ni or gold or au or silver or ag or solder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:43
S63	220	(wafer or substrate) near (periphery or edge or peripheral or outer) near4 (barrier or ring or seal or sealing or hermetic) same (wafer or substrate) near3 (stack or stacked or stacking or bonding or bonded or bond or 3d or "3-d" or three near dimensional)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:24
S30	210	(wafer or substrate) near (periphery or edge or peripheral or outer) near4 (barrier or spacer or ring or seal or sealing) same (wafer or substrate) near3 (stack or stacked or stacking or bonding or bonded or bond or 3d or "3-d" or three near dimensional)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:23
S23	82	(scribe or scribing or cleave or cleaving or singulating or singulation or dice or dicing) near8 (barrier or seal or sealed or sealing) near4 (hermetic$5)	US-PGPUB; USPAT	OR	ON	2005/07/20 14:59
S62	109	(scribe or scribing or cleave or cleaving or singulating or singulation or dice or dicing) near8 (barrier or seal or sealed or sealing) near4 (hermetic$5)	US-PGPUB; USPAT	OR	ON	2005/07/20 14:59
S61	5	("5699611").URPN.	USPAT	OR	ON	2005/07/20 14:57

S58	5	flip adj chip same (seal or sealing or sealed) near2 (hermetic$5) near5 (edge or periphery or peripheral or outside or outer or circumference or circumscrib$3 or scribe)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 14:53
S59	5	flip adj chip same (seal or sealing or sealed) near2 (hermetic$5) near5 (pillar or ridge or barrier or line or elevated or raised)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 14:53
S9	287	flip adj chip same (seal or sealing or sealed) near2 (hermetic$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 14:51
S57	335	flip adj chip same (seal or sealing or sealed) near2 (hermetic$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 14:51
S55	65	((die or wafer or chip or substrate) near2 (bond or bonding or attachment or attaching or bonded or attached) or flip adj chip) and (barrier or seal or sealing) near3 (edge or periphery or peripheral or outside or outer) near3 (wafer or substrate) near15 (metal or metallic or copper or cu or gold or au or silver or ag or nickel or ni or aluminum or al)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 14:40
S4	47	((die or wafer or chip or substrate) near2 (bond or bonding or attachment or attaching or bonded or attached) or flip adj chip) and (barrier or seal or sealing) near3 (edge or periphery or peripheral or outside or outer) near3 (wafer or substrate) near15 (metal or metallic or copper or cu or gold or au or silver or ag or nickel or ni or aluminum or al)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 14:34
S54	176	((die or wafer or chip) near2 (bond or bonding or attachment or attaching or bonded or attached) or flip adj chip) and (barrier or corrosion or contamination or crack or sealing or seal) near3 (edge or periphery or peripheral or outside or outer) near3 (metal or copper or cu or metallic or aluminum or gold or silver)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 14:19